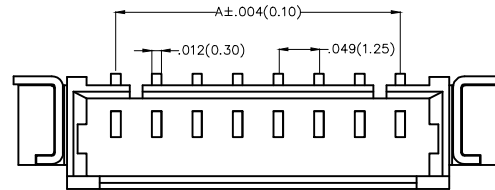


REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
2		Add description	14/JUL/23	YYQ	LEO

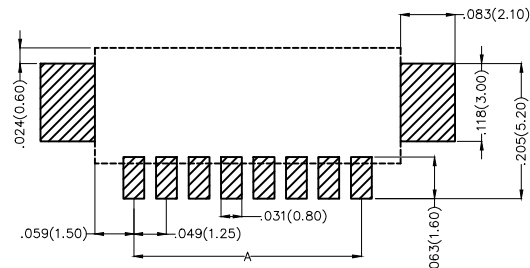
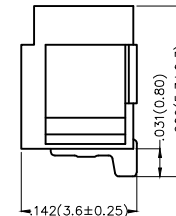
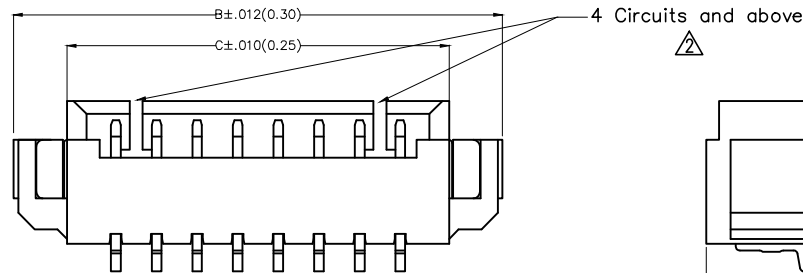
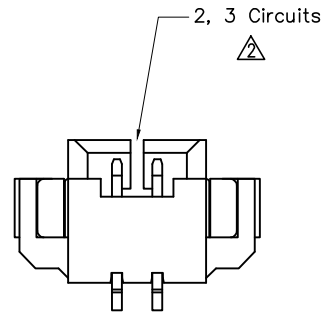


Electrical

Current Rating:1.0A AC(rms)/DC
Voltage Rating:125V AC(rms)/DC
Contact Resistance:20 mΩ Max
Insulation Resistance:100 MΩ MIN
Withstanding Voltage:250V AC r.m.s
Temperature Range-Operating: -40℃~+85℃

Material and Plating

Housing:PA9T(UL 94V-0)
Contact Pin:Phosphor bronze/ Tin plated
Solder Tab:Copper alloy/ Tin plated



Recommended P.C.Board Layout

Ordering Information

FWF 125 04 — S XX B X 4 W5 M
1 2 3 4 5 6 7 8 9 10

1	Category FWF-Wafer	2	Series Number 125-Pitch1.25mm	3	Distinction No. 04	4	Row Option S-Single Row	5	Circuits XX	6	Entry Angle B-90° Angle
7	Plating 2-Tin Plated	8	Material-Resin 4-PA9T	9	Color-Resin W5-Natural	10	Packaging M-Reel				

 THIRD ANGLE PROJECTION		GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY	DATE	PART NO. FWF12504-SXXBX4W5M	ITEM NO. FWF12504	 Leader Of Industry	
				FRANK	8/JUL/13				
DESIGN UNITS Inch (metric)		X.±.012(0.30)	X.±5°	CHECKED BY	DATE	TITLE Wire to Board (Wafer) Pitch 1.25mm 90° Angle (SMT)		REV 2	SHEET NO. 1/3
		X.X±.008(0.20)	.X°±2°	JACOB	8/JUL/13				
		SCALE 5:1	SIZE A4	X.XX±.006(0.15)	.XX°±1°	DRAWN BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
		X.XXX±.004(0.10)	.XXX°±0.5°	CHERRY	8/JUL/13				

A

B

C

D

E

F

A

B

C

D

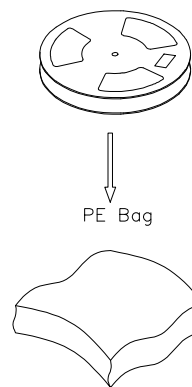
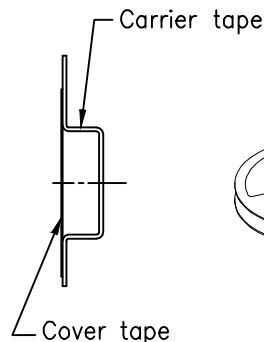
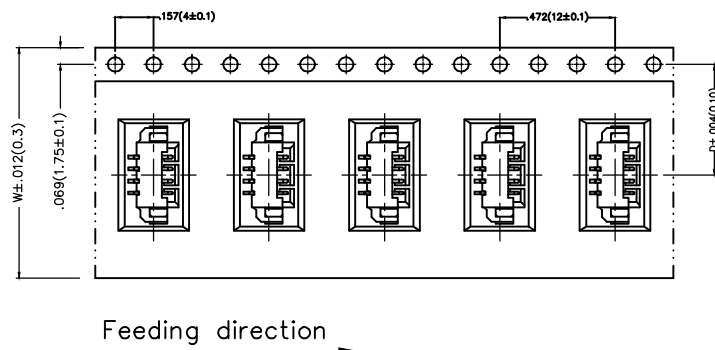
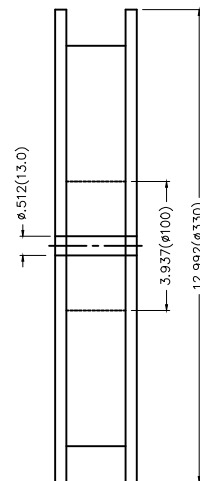
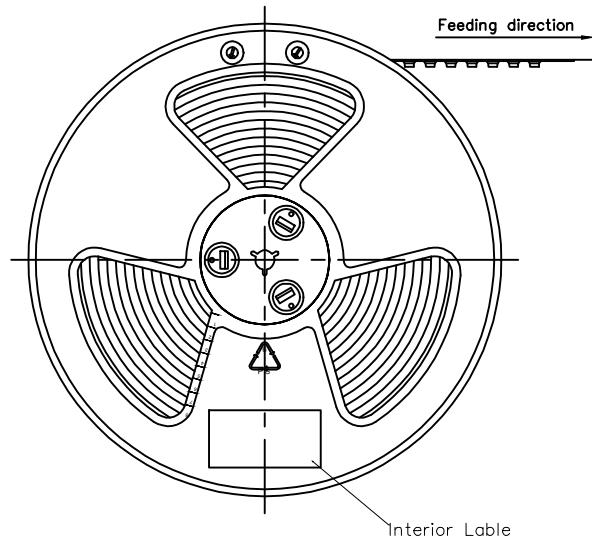
E

F

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

Circuits (n)	Part No.	Dimensions(in/mm)		
		A	B	C
2	FWF12504-S02B24W5M	.049(1.25)	.297(7.55)	.167(4.25)
3	FWF12504-S03B24W5M	.098(2.50)	.346(8.80)	.217(5.50)
4	FWF12504-S04B24W5M	.147(3.75)	.396(10.05)	.266(6.75)
5	FWF12504-S05B24W5M	.197(5.00)	.445(11.30)	.315(8.00)
6	FWF12504-S06B24W5M	.246(6.25)	.494(12.55)	.364(9.25)
7	FWF12504-S07B24W5M	.295(7.50)	.543(13.80)	.413(10.50)
8	FWF12504-S08B24W5M	.344(8.75)	.593(15.05)	.463(11.75)
9	FWF12504-S09B24W5M	.394(10.00)	.642(16.30)	.512(13.00)
10	FWF12504-S10B24W5M	.443(11.25)	.691(17.55)	.561(14.25)
11	FWF12504-S11B24W5M	.492(12.50)	.740(18.80)	.610(15.50)
12	FWF12504-S12B24W5M	.541(13.75)	.789(20.05)	.659(16.75)
13	FWF12504-S13B24W5M	.591(15.00)	.839(21.30)	.709(18.00)
14	FWF12504-S14B24W5M	.640(16.25)	.888(22.55)	.758(19.25)
15	FWF12504-S15B24W5M	.689(17.50)	.937(23.80)	.807(20.50)

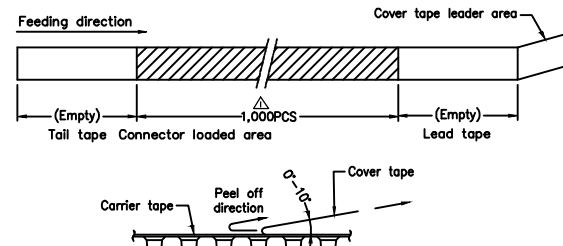
 THIRD ANGLE PROJECTION		GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 8/JUL/13	PART NO. FWF12504-SXXBX4W5M	ITEM NO. FWF12504	 Leader Of Industry	
		X.±.012(0.30)	X.±5°	CHECKED BY	DATE	TITLE			
DESIGN UNITS Inch (metric)		X.X±.008(0.20)	X.±2°	JACOB	8/JUL/13	Wire to Board (Wafer) Pitch 1.25mm 90° Angle (SMT)		REV 2	SHEET NO. 2/3
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							
SCALE 5:1	SIZE A4	X.XX±.006(0.15)	.XX±1°	DRAWN BY CHERRY	DATE 8/JUL/13				
		X.XXX±.004(0.10)	.XXX±0.5°						



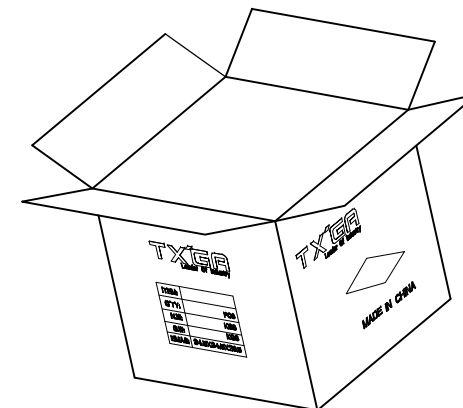
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1	△	MPQ 1500PCS/Reel Change to 1000Pcs/Reel	20150811	CHERRY	JACOB

Note:

1. 10 sprocket hole cumulative tolerance ± 0.2
2. Carrier camber is within 1.0mm in 100mm
3. Material: White Conductive polystyrene Alloy 100% recyclable
4. All dimensions meet EIA-481-3 requirements
5. Component load per 13" reel: 1,000 pcs



Circuits (n)	Dimensions(in/mm)		Circuits (n)	Dimensions(in/mm)	
	D	W		D	W
2	.295(7.50)	.630(16.00)	10	.559(14.20)	1.260(32.00)
3	.295(7.50)	.630(16.00)	11	.559(14.20)	1.260(32.00)
4	.453(11.50)	.945(24.00)	12	.559(14.20)	1.260(32.00)
5	.453(11.50)	.945(24.00)	13	.795(20.20)	1.732(44.00)
6	.453(11.50)	.945(24.00)	14	.795(20.20)	1.732(44.00)
7	.559(14.20)	1.260(32.00)	15	.795(20.20)	1.732(44.00)
8	.559(14.20)	1.260(32.00)			
9	.559(14.20)	1.260(32.00)			



 THIRD ANGLE PROJECTION		GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 8/JUL/13	PART NO. FWF12504-SXXBX4W5M	ITEM NO. FWF12504	 Leader Of Industry		
		X.±0.12(0.30)	X.±5°	CHECKED BY	DATE	TITLE				
DESIGN UNITS Inch (metric)		X.X±.008(0.20)	.X"±2"	JACOB	8/JUL/13	Wire to Board (Wafer) Pitch 1.25mm 90° Angle (SMT)		REV 2	SHEET NO. 3/3	
		X.XX±.006(0.15)	.XX"±1"	DRAWN BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
		X.XXX±.004(0.10)	.XXX"±0.5°	CHERRY	8/JUL/13					
SCALE 5:1	SIZE A4									